


Qualification Test Report

501- 99061 Rev.A

Product Specification : 108-99061

Date : 15Oct2015

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| | | | | Prepared by Andy.Xiao | |  | TE Connectivity Shanghai Ltd | | | |
| | | | | Reviewed by Hapye Wu | | | | | | |
| | | | | Approved by Hapye.Wu | | | | | NO | |
| | | | | | | | | | 501-99061 | REV A |
| 1 | Initial release | A.X | 15Oct 2015 | PAGE 1 of 9 | TITLE USB 3.0 Receptacle | | | | | |
| LTR | REVISION RECORD | DR | DATE | | | | | | | |

1. Introduction

1.1 Objective

Testing was performed on the USB Type-C Receptacle and Plug Lead Free Version connectors to determine if it meets the requirements of Design Objective, 108-99061, Rev. 1.

1.2 Scope

This report covers the electrical, mechanical and environmental performance requirements of the USB Type-C Receptacle and Plug Lead Free Version connectors.

1.3 Conclusion

The USB Type-C Receptacle and Plug Lead Free Version connectors listed in paragraph 1.5, meets the electrical, mechanical and environmental performance requirements of Product Specification, 108-99061, Rev. 1.

1.4 Product Description

The USB Type-C Lead Free Version connectors are cable mounted plugs and printed circuit mounted receptacles. The contacts are made of a copper alloy with gold over palladium nickel plating in contact area, tin plating on solder area all over nickel plating. The housing material is thermoplastic UL94V-0 rated.

1.5 Test Samples

The test samples were representative of normal production lots, and samples identified with the following part numbers were used for test:

| Test Group | Quantity | Part Number | Description |
|--|-----------------------|-------------|---------------------|
| A-1, A-2,A-3,A-4,A-7, B-1, B-5 ² ,B-6,B-7, C-1 ³ . | Refer to test result. | 2129691 | Receptacle Assembly |

1.6 Environmental Conditions

Unless otherwise stated, the following environmental conditions prevailed during test:

Temperature: 15°C to 35°C

Relative Humidity: 25 to 85%

² To be reported in Critical Dimension Inspection Report

³ Additional test, not part of USB Type C Compliance Requirements

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2. Test Method

Test requirement and Procedures summary

Table.1

| Test Item | Procedures | Requirements |
|---------------------------------|---|--|
| Electrical | | |
| Low Level Contact Resistance | EIA 364-23 The low level contact resistance (LLCR) measurement is made across the plug and receptacle mated contacts and does not include any internal paddle cards or substrates of the plug or receptacle. Measure at 20mV (max) open circuit at 100 mA | 40 mΩ (Max) initial for VBUS, GND and all other contacts. Maximum change (delta) of +/-10 mΩ after environmental stresses. |
| Continuity | See USB Type C Compliance Document Appendix E. | No discontinuities or shorts allowed. |
| Dielectric Withstanding Voltage | EIA-364-20, Method B. Applicable to both receptacle and plug. 100VAC (rms) for 1 minute at sea level. | No break down shall occur when voltage is applied between adjacent contacts of unmated and mated connectors |
| Insulation Resistance | EIA 364-21 Applicable to both receptacle and plug. Apply 500V DC Apply the above specified voltage between adjacent contacts for 2 minute. | >100 MΩ insulation resistance between adjacent contacts of unmated and mated connectors |
| Current Rating | EIA 364-70, Method 2. See USB Type C Compliancy Document Appendix C. A current of 5.0 A shall be applied collectively to VBUS pins (i.e., pins A4, A9, B4, and B9) and 1.25 A applied to the VCONN pin (i.e., B5 of the plug connector) with the return path through the corresponding GND pins (i.e., pins A1, A12, B1, and B12). A minimum current of 0.25 A shall also be applied individually to all the other contacts. Allow to stabilize. Note: special T-rise test boards design per the guidelines in Appendix C of the USB Type C Compliancy Document are to be used. | Temperature rise of the outside shell surface of the mated connector pair above the VBUS and GND contacts shall not exceed 30°C above ambient temperature. |

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Table.1 (Cont.)

| Test Item | Procedures | Requirements |
|-------------------------------|--|---|
| Mechanical | | |
| Critical Dimension Inspection | See USB Type C Compliancy Document Appendix B. | Meet all critical dimension requirements defined in Appendix B. |
| Insertion Force | EIA-364-13 Maximum rate 12.5mm/min | Between 5N and 20N |
| Extraction Force | EIA-364-13 Maximum rate 12.5mm/min | Within the range of 8 N to 20 N, measured after a preconditioning of five insertion/extraction cycles (i.e., the sixth extraction). After an additional twenty-five insertion/extraction cycles, the extraction force shall be measured again (i.e., the thirty-second extraction) and the extraction force shall be within: a) 33 % of the initial reading, and b) within the range of 8 N to 20 N. The extraction force shall be within the range of 6 N to 20 N after 10,000 insertion/extraction cycles. |
| Durability | EIA 364-09 10,000 cycles | No evidence of physical damage |
| Durability (Preconditioning) | EIA 364-09 50 cycles | No evidence of physical damage |
| Reseating | Manually unplug/plug the connector. Perform 3 such cycles | No evidence of physical damage |
| Cable Pull-Out | EIA 364-38, Method A, 40N axial load, >1 min, Clamping one end of the plug | No physical damage to the cable assembly shall occur |
| Cable Flexing | EIA 364-41, Condition 1, Dimension X = 3.7 times the cable diameter and 100 cycles in each of two planes 120°arc. | No physical damage or discontinuity over 1ms during flexing shall occur to the cable assembly. |
| 4-Axis Continuity Test | See USB Type C Compliancy Document Appendix D for detailed test fixtures and procedures. Plug and Receptacle: Subject the mating interface to the moments defined in USB Type C Compliancy Document Appendix D for at least 10 seconds. | No discontinuities greater than 1 microsecond duration in any of the four orientations tested. |

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Table.1 (End)

| Test Item | Procedures | Requirements |
|------------------------------------|--|---|
| Environmental | | |
| Temperature Life | EIA-364-17, Method A 105°C, 120hrs | |
| Temperature Life (Preconditioning) | EIA-364-17, Method A 105°C, 72hrs | |
| Thermal Shock | EIA-364-32, Method A, Condition I, duration A-4 (-55°+85°C, 10 cycles) | |
| Cyclic Temperature and Humidity | EIA-364-31, Method III, w/o optional cold shock and vibration. Exceptions per EIA-364-1000: - Cycle between 25°C/80%RH and 65°C/50%RH. - Ramp 0.5hr, dwell 1hr, dwell starts when conditions are stabilized. - 24 cycles total - Allowable variation ±3°C and ±3%RH | |
| Vibration | EIA-364-28, Condition VII-D, 15min in each of 3 mutually perpendicular directions. Both mating halves should be fixed rigidly. (Power Spectral Density 0.02g ² /Hz, Overall rms 3.10g) | No evidence of physical damages and no discontinuity longer than 1 microsecond. |
| Mixed Flowing Gas | EIA-364-65, class IIA, 112hrs unmated, 56hrs mated (168hrs total). | |
| Thermal Disturbance | Cycle the mated connector pair 10 times between 15°C and 85°C. - ramp > 2°C/min - dwell > 5 mins (ensure contacts reach temperature) - Humidity not controlled | |
| Other | | |
| Solderability | Category 3 Steam Age RMA Class 1 flux immerse in molten solder at a temperature of +255°C ± 5°C at rate of 25.4 mm ± 6.35 mm per second. Hold in solder for 5 +0/-0.5 seconds. To include solder pins and mounting pads. | Solderable area shall have a minimum of 95% solder coverage. |

NOTE: (1) Shall meet visual requirements, show no physical damage, and meet requirements of additional tests as specified in the Product Qualification and Prequalification Test Sequence shown in table 2.

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3. Qualifications Test Sequence

Table.2

| Test | A-1 | A-2 | A-3 | A-4 | A-7 | B-1 | B-5 ² | B-6 | B-7 | C-1 ³ |
|------------------------------------|-------|---------|-------|----------|-----|-----|------------------|-----|-----|------------------|
| Critical Dimensions | | | | | | | 1 | | | |
| Low Level Contact Resistance | 1,4,6 | 1,4,6,8 | 1,4,6 | 1,4,6,8, | 2,6 | | | | | |
| Durability | | | | | 3 | | | | | |
| Durability (Preconditioning) | 2 | 2 | 2 | 2 | | | | | | |
| Insertion Force | | | | | 4 | | | | | |
| Extraction Force | | | | | 5, | | | | | |
| Temperature Life | 3 | | | 3 | | | | | | |
| Temperature Life (Preconditioning) | | | 3 | | | | | | | |
| Reseating | 5 | 7 | | | | | | | | |
| Thermal Shock | | 3 | | | | | | | | |
| Cyclic Temperature and Humidity | | 5 | | | | | | | | |
| Vibration | | | 5 | | | | | | | |
| Mixed Flowing Gas | | | | 5 | | | | | | |
| Thermal Disturbance | | | | 7 | | | | | | |
| Continuity | | | | | | | | | 1 | |
| Dielectric Withstanding Voltage | | | | | 1,7 | | | | 2 | |
| Insulation Resistance | | | | | 8 | | | | | |
| Current Rating | | | | | | | | 1 | | |
| Cable Pull-Out | | | | | | 1 | | | | |
| Cable Flexing | | | | | | 2 | | | | |
| 4-Axis Continuity Test | | | | | | 3 | | | | |
| Solderability | | | | | | | | | | 1 |

Signal Integrity Testing

The following cable assembly specific test groups are to be reported in a separate test report:

- Test Group B-2: USB 2.0 and Low Speed Signal Tests of Type-C Cable and Adaptor Assemblies
- Test Group B-3: USB SuperSpeed Signal Tests of Type-C Cable and Adaptor Assemblies
- Test Group B-4: USB Type-C Cable and Adaptor Assembly Shielding Effectiveness Test Requirements and Test Sequence as per USB Type C Compliance Document.

² To be reported in Critical Dimension Inspection Report

³ Additional test, not part of USB Type C Compliance Requirements

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4 Test Result:

| | Test Item | No. | Condition | Test Result | | | Requirement | Judgment |
|------------------------------|-------------------------------|-----------|-----------|-----------------------------|-------|-------|------------------|----------|
| | | | | Max | Min | Ave | | |
| Group A-1 | LLCR_PINA | 5 | Initial | 38.65 | 28.97 | 32.78 | <40 mΩ | Pass |
| | LLCR_PINB | 5 | Initial | 13.06 | 5.42 | 7.18 | <40 mΩ | Pass |
| | Durability (preconditioning) | 5 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| | Temperature life (Heat Aging) | 5 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| | LLCR_PINA(ΔR) | 5 | Final | 6.26 | -6.85 | 0.22 | <10 mΩ | Pass |
| | LLCR_PINB (ΔR) | 5 | Final | 1.43 | -5.61 | -0.45 | <10 mΩ | Pass |
| | Reseating | 5 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| | LLCR_PINA(ΔR) | 5 | Final | 8.02 | -9.30 | -1.41 | <10 mΩ | Pass |
| | LLCR_PINB (ΔR) | 5 | Final | 2.97 | -3.31 | -0.20 | <10 mΩ | Pass |
| | Group A-2 | LLCR_PINA | 5 | Initial | 38.74 | 26.79 | 33.12 | <40 mΩ |
| LLCR_PINB | | 5 | Initial | 12.01 | 5.88 | 7.11 | <40 mΩ | Pass |
| Durability (preconditioning) | | 5 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| Thermal Shock | | 5 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| LLCR_PINA(ΔR) | | 5 | Final | 9.30 | 5.29 | 6.83 | <10 mΩ | Pass |
| LLCR_PINB (ΔR) | | 5 | Final | 7.08 | -7.33 | -1.13 | <10 mΩ | Pass |
| Humidity, Steady State | | 5 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| LLCR_PINA(ΔR) | | 5 | Final | 7.93 | 5.42 | 6.92 | <10 mΩ | Pass |
| LLCR_PINB (ΔR) | | 5 | Final | 1.24 | -4.53 | -0.18 | <10 mΩ | Pass |
| Reseating | | 5 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| LLCR_PINA(ΔR) | | 5 | Final | 8.32 | 5.77 | 6.86 | <10 mΩ | Pass |
| LLCR_PINB (ΔR) | | 5 | Final | 7.39 | -6.45 | -0.76 | <10 mΩ | Pass |

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|----------------|-------------------------------|-------|---------|---|-------|--------|------------------|------|
| Group A-3 | LLCR_PINA | 5 | Initial | 37.85 | 24.77 | 31.81 | <40 mΩ | Pass |
| | LLCR_PINB | 5 | Initial | 9.31 | 5.55 | 6.79 | <40 mΩ | Pass |
| | Durability (preconditioning) | 5 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| | Temperature life (Heat Aging) | 5 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| | LLCR_PINA(ΔR) | 5 | Final | 8.76 | 5.46 | 6.62 | <10 mΩ | Pass |
| | LLCR_PINB (ΔR) | 5 | Final | 7.04 | -5.12 | 0.07 | <10 mΩ | Pass |
| | Vibration (Random) | 5 | Initial | No discontinuities of 1 microsecond or longer duration occurred | | | No abnormalities | Pass |
| | LLCR_PINA(ΔR) | 5 | Final | 8.03 | 5.34 | 6.68 | <10 mΩ | Pass |
| | LLCR_PINB (ΔR) | 5 | Final | 5.91 | -6.93 | -0.93 | <10 mΩ | Pass |
| Group A-4 | LLCR_PINA | 5 | Initial | 38.76 | 28.52 | 32.79 | <40 mΩ | Pass |
| | LLCR_PINB | 5 | Initial | 9.04 | 5.26 | 7.18 | <40 mΩ | Pass |
| | Durability (preconditioning) | 5 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| | Temperature life (Heat Aging) | 5 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| | LLCR_PINA(ΔR) | 5 | Final | 8.95 | -8.28 | 1.03 | <10 mΩ | Pass |
| | LLCR_PINB (ΔR) | 5 | Final | 2.49 | -3.18 | 0.18 | <10 mΩ | Pass |
| | Mixed Flowing Gas | 5 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| | LLCR_PINA(ΔR) | 5 | Final | 8.08 | -9.98 | 0.67 | <10 mΩ | Pass |
| | LLCR_PINB (ΔR) | 5 | Final | 1.84 | -2.25 | 0.03 | <10 mΩ | Pass |
| | Humidity, Steady State | 5 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| | LLCR_PINA(ΔR) | 5 | Final | 5.77 | -7.64 | -0.35 | <10 mΩ | Pass |
| | LLCR_PINB (ΔR) | 5 | Final | 1.62 | -2.04 | 0.05 | <10 mΩ | Pass |
| | Reseating | 5 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| | LLCR_PINA(ΔR) | 5 | Final | 8.92 | 6.18 | 7.28 | <10 mΩ | Pass |
| LLCR_PINB (ΔR) | 5 | Final | 2.64 | -2.14 | 0.10 | <10 mΩ | Pass | |

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|---------------------------|-----------------------------------|----|---------|--|-------|-------|--|------|
| Group A-7 | Dielectric withstanding Voltage | 10 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| | LLCR_PINA | 10 | Initial | 38.47 | 27.35 | 32.87 | <40 mΩ | Pass |
| | LLCR_PINB | 10 | Initial | 13.03 | 5.30 | 7.52 | <40 mΩ | Pass |
| | Durability (No abnormalities) | 10 | Final | No physical damage occurred | | | No abnormalities | Pass |
| | Un-mating Force | 10 | Initial | 17.36 | 12.03 | 14.96 | 8N ~ 20 N | Pass |
| | Mating Force | 10 | Initial | 18.13 | 10.09 | 15.28 | 5N ~20 N | Pass |
| | Durability (Repeated mate/unmate) | 10 | Final | No physical damage occurred | | | No abnormalities | Pass |
| | Un-mating Force | 10 | Final | 12.42 | 6.37 | 9.64 | 6N ~ 20 N | Pass |
| | Mating Force | 10 | Final | 16.76 | 9.07 | 12.60 | 5N ~20 N | Pass |
| | LLCR_PINA | 10 | Final | 6.44 | -8.65 | -4.21 | <10 mΩ | Pass |
| | LLCR_PINB | 10 | Final | 2.31 | -6.7 | -0.6 | <40 mΩ | Pass |
| | Dielectric withstanding Voltage | 10 | Final | No physical damage occurred | | | No abnormalities | Pass |
| | Insulation resistance | 10 | Final | 1109 | 277 | 799 | >100MΩ | Pass |
| Group B-1 | Cable Pull-Out | 10 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| | Cable Flexing | 10 | Initial | No physical damage occurred | | | No abnormalities | Pass |
| | 4-Axis Continuity Test | 10 | Final | No physical damage occurred | | | No abnormalities | Pass |
| Group B-6 | Current Rating | 5 | Initial | 21.82 | 19.50 | 21.31 | ΔT 30°C Max. | Pass |
| Group C-1 ³ | Solderability | 5 | Initial | Contact Pin was ok Mounting tab was >80% solder coverage | | | There are minimum of 95% solder coverage | Pass |

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